

TEMIC

Siliconix

ND2406L/2410L, BSS129**N-Channel Depletion-Mode MOS Transistors****Product Summary**

Part Number	V _{(BR)DSV} Min (V)	r _{D(on)} Max (Ω)	V _{GS(off)} (V)	I _D (A)
ND2406L	240	6	-1.5 to -4.5	0.23
ND2410L		10	-0.5 to -2.5	0.18
BSS129	230	20	-0.7 (min)	0.15

For applications information see AN901.

Features

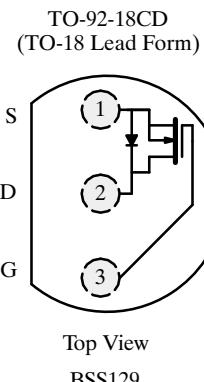
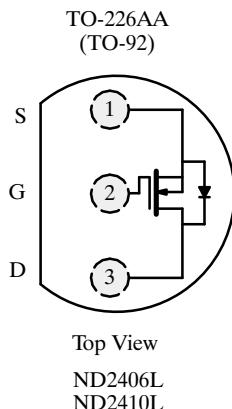
- High Breakdown Voltage: 260 V
- Normally “On” Low r_{D(on)} Switch: 3.5 Ω
- Low Input and Output Leakage
- Low-Power Drive Requirement
- Low Input Capacitance

Benefits

- Full-Voltage Operation
- Low Offset Voltage
- Low Error Voltage
- Easily Driven Without Buffer
- High-Speed Switching

Applications

- Normally “On” Switching Circuits
- Current Sources/Limiters
- Power Supply, Converter Circuits
- Solid-State Relays
- Telecom Switches

**Absolute Maximum Ratings (T_A = 25°C Unless Otherwise Noted)**

Parameter	Symbol	ND2406L	ND2410L	BSS129	Unit
Drain-Source Voltage	V _{DS}	240	240	230	V
Gate-Source Voltage	V _{GS}	±30	±30	±20	
Continuous Drain Current (T _J = 150°C)	T _A = 25°C	I _D	0.23	0.18	A
	T _A = 100°C		0.14	0.12	
Pulsed Drain Current	I _{DM}	0.9	0.9	0.6	
Power Dissipation	T _A = 25°C	P _D	0.8	0.8	W
	T _A = 100°C		0.32	0.32	
Maximum Junction-to-Ambient	R _{thJA}	156	156	125	°C/W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150			°C

Notes

a. Pulse width limited by maximum junction temperature.

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Specifications^a

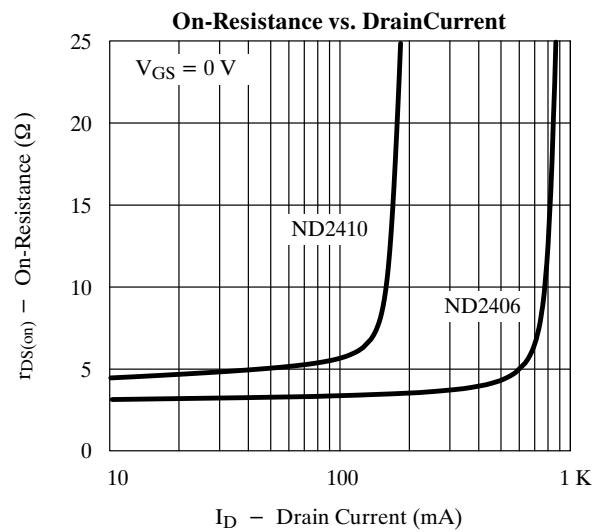
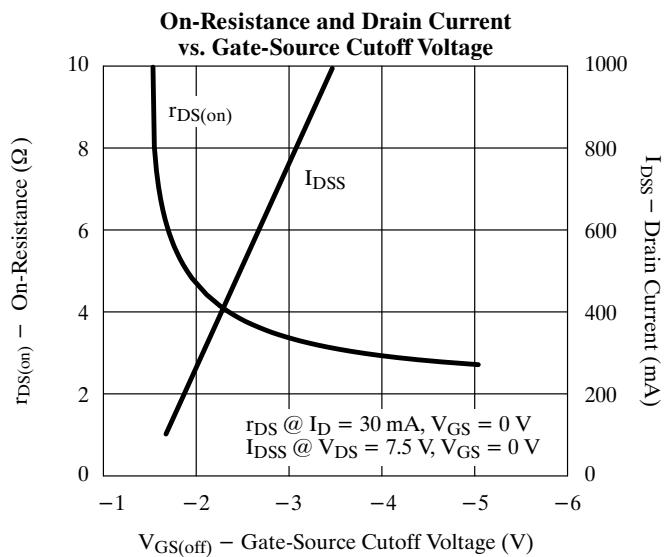
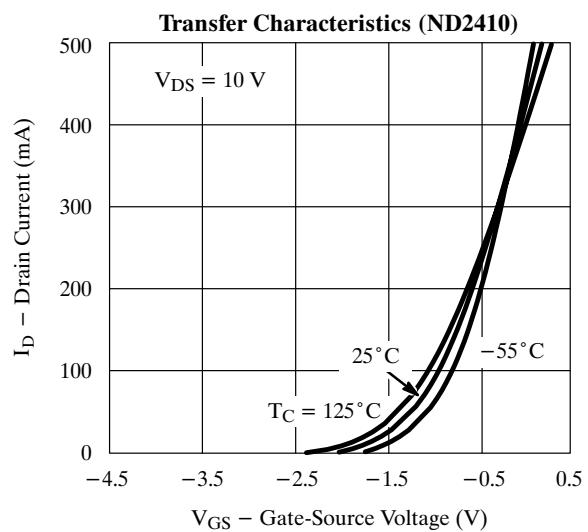
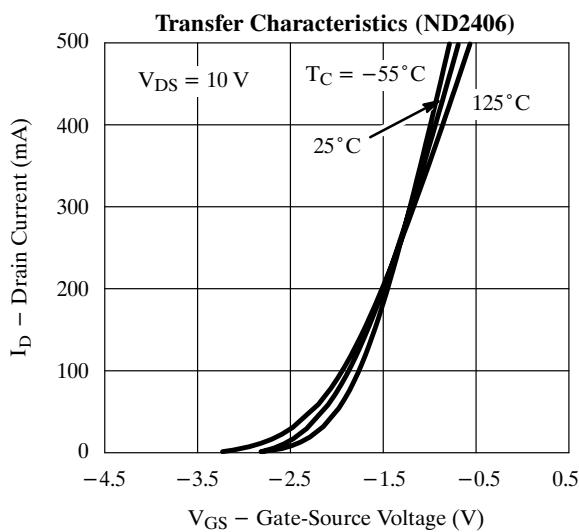
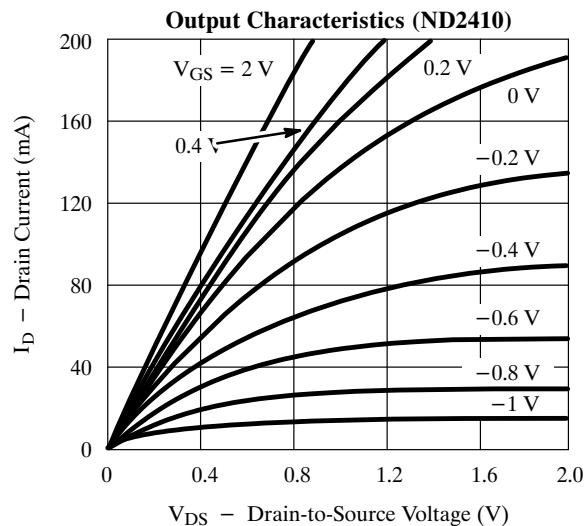
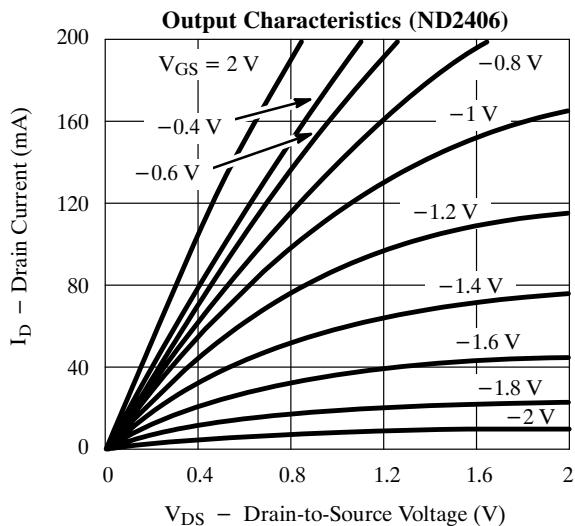
Parameter	Symbol	Test Conditions	Typ ^b	Limits						Unit	
				ND2406L		ND2410L		BSS129			
				Min	Max	Min	Max	Min	Max		
Static											
Drain-Source Breakdown Voltage	V _{(BR)DSV}	V _{GS} = -9 V, I _D = 10 µA	260	240						V	
		V _{GS} = -5 V, I _D = 10 µA	260			240					
		V _{GS} = -3 V, I _D = 250 µA	260					230			
Gate-Source Cutoff Voltage	V _{GS(off)}	V _{DS} = 5 V, I _D = 10 µA		-1.5	-4.5	-0.5	-2.5				
		V _{DS} = 3 V, I _D = 1 mA						-0.7			
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±10		±10		±100	nA	
		T _J = 125°C			±50		±50				
Drain Cutoff Current	I _{D(off)}	V _{DS} = 180 V, V _{GS} = -9 V			1					µA	
		T _J = 125°C			200						
		V _{DS} = 180 V, V _{GS} = -5 V					1				
		T _J = 125°C					200				
Drain-Saturation Current ^c	I _{DSS}	V _{DS} = 10 V, V _{GS} = 0 V	350	40		40				mA	
		V _{GS} = 2 V, I _D = 30 mA	3.3								
Drain-Source On-Resistance ^c	r _{DS(on)}	V _{GS} = 0 V, I _D = 30 mA	3.5		6	10				Ω	
		T _J = 125°C	5.6		15	25					
		V _{GS} = 0 V, I _D = 14 mA	4						20		
Forward Transconductance ^c	g _{fs}	V _{DS} = 25 V, I _D = 250 mA	375				140			mS	
			110								
Common Source Output Conductance ^c	g _{os}	V _{DS} = 10 V, I _D = 30 A		70						µS	
Dynamic											
Input Capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = -5 V f = 1 MHz	70		120		120			pF	
Output Capacitance	C _{oss}		20		30		30				
Reverse Transfer Capacitance	C _{rss}		10		15		15				
Switching^d											
Turn-On Time	t _{d(on)}	V _{DD} = 25 V, R _L = 830 Ω I _D ≈ 30 mA, V _{GEN} = -5 V R _G = 25 Ω	15							ns	
	t _r		75								
Turn-Off Time	t _{d(off)}		40								
	t _f		100								

Notes

- a. T_A = 25°C unless otherwise noted.
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Pulse test: PW ≤ 300 µs duty cycle ≤ 2%.
- d. Switching time is essentially independent of operating temperature.

VDDV24

Typical Characteristics (25°C Unless Otherwise Noted)



ND2406L/2410L, BSS129

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Typical Characteristics (25°C Unless Otherwise Noted) (Cont'd)

